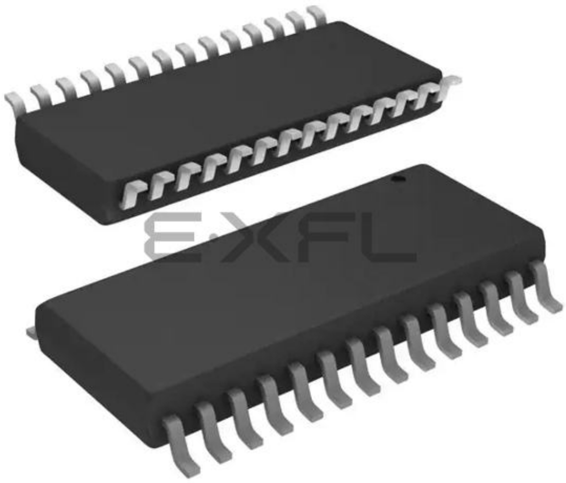

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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	16-Bit
Speed	32MHz
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	24
Program Memory Size	32KB (11K x 24)
Program Memory Type	FLASH
EEPROM Size	512 x 8
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 13x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic24f32ka302t-i-so

2.2 Power Supply Pins

2.2.1 DECOUPLING CAPACITORS

The use of decoupling capacitors on every pair of power supply pins, such as V_{DD}, V_{SS}, AV_{DD} and AV_{SS}, is required.

Consider the following criteria when using decoupling capacitors:

- **Value and type of capacitor:** A 0.1 µF (100 nF), 10-20V capacitor is recommended. The capacitor should be a low-ESR device, with a resonance frequency in the range of 200 MHz and higher. Ceramic capacitors are recommended.
- **Placement on the printed circuit board:** The decoupling capacitors should be placed as close to the pins as possible. It is recommended to place the capacitors on the same side of the board as the device. If space is constricted, the capacitor can be placed on another layer on the PCB using a via; however, ensure that the trace length from the pin to the capacitor is no greater than 0.25 inch (6 mm).
- **Handling high-frequency noise:** If the board is experiencing high-frequency noise (upward of tens of MHz), add a second ceramic type capacitor in parallel to the above described decoupling capacitor. The value of the second capacitor can be in the range of 0.01 µF to 0.001 µF. Place this second capacitor next to each primary decoupling capacitor. In high-speed circuit designs, consider implementing a decade pair of capacitances as close to the power and ground pins as possible (e.g., 0.1 µF in parallel with 0.001 µF).
- **Maximizing performance:** On the board layout from the power supply circuit, run the power and return traces to the decoupling capacitors first, and then to the device pins. This ensures that the decoupling capacitors are first in the power chain. Equally important is to keep the trace length between the capacitor and the power pins to a minimum, thereby reducing PCB trace inductance.

2.2.2 TANK CAPACITORS

On boards with power traces running longer than six inches in length, it is suggested to use a tank capacitor for integrated circuits, including microcontrollers, to supply a local power source. The value of the tank capacitor should be determined based on the trace resistance that connects the power supply source to the device, and the maximum current drawn by the device in the application. In other words, select the tank capacitor so that it meets the acceptable voltage sag at the device. Typical values range from 4.7 µF to 47 µF.

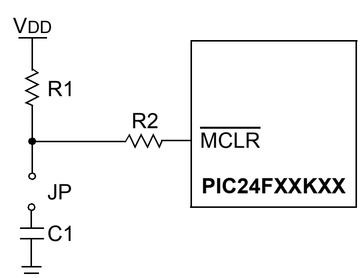
2.3 Master Clear ($\overline{\text{MCLR}}$) Pin

The $\overline{\text{MCLR}}$ pin provides two specific device functions: Device Reset, and Device Programming and Debugging. If programming and debugging are not required in the end application, a direct connection to V_{DD} may be all that is required. The addition of other components, to help increase the application's resistance to spurious Resets from voltage sags, may be beneficial. A typical configuration is shown in Figure 2-1. Other circuit designs may be implemented, depending on the application's requirements.

During programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{\text{MCLR}}$ pin. Consequently, specific voltage levels (V_{IH} and V_{IL}) and fast signal transitions must not be adversely affected. Therefore, specific values of R1 and C1 will need to be adjusted based on the application and PCB requirements. For example, it is recommended that the capacitor, C1, be isolated from the $\overline{\text{MCLR}}$ pin during programming and debugging operations by using a jumper (Figure 2-2). The jumper is replaced for normal run-time operations.

Any components associated with the $\overline{\text{MCLR}}$ pin should be placed within 0.25 inch (6 mm) of the pin.

FIGURE 2-2: EXAMPLE OF $\overline{\text{MCLR}}$ PIN CONNECTIONS



Note 1: R1 ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the $\overline{\text{MCLR}}$ pin V_{IH} and V_{IL} specifications are met.

2: R2 ≤ 470Ω will limit any current flowing into $\overline{\text{MCLR}}$ from the external capacitor, C, in the event of $\overline{\text{MCLR}}$ pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the $\overline{\text{MCLR}}$ pin V_{IH} and V_{IL} specifications are met.

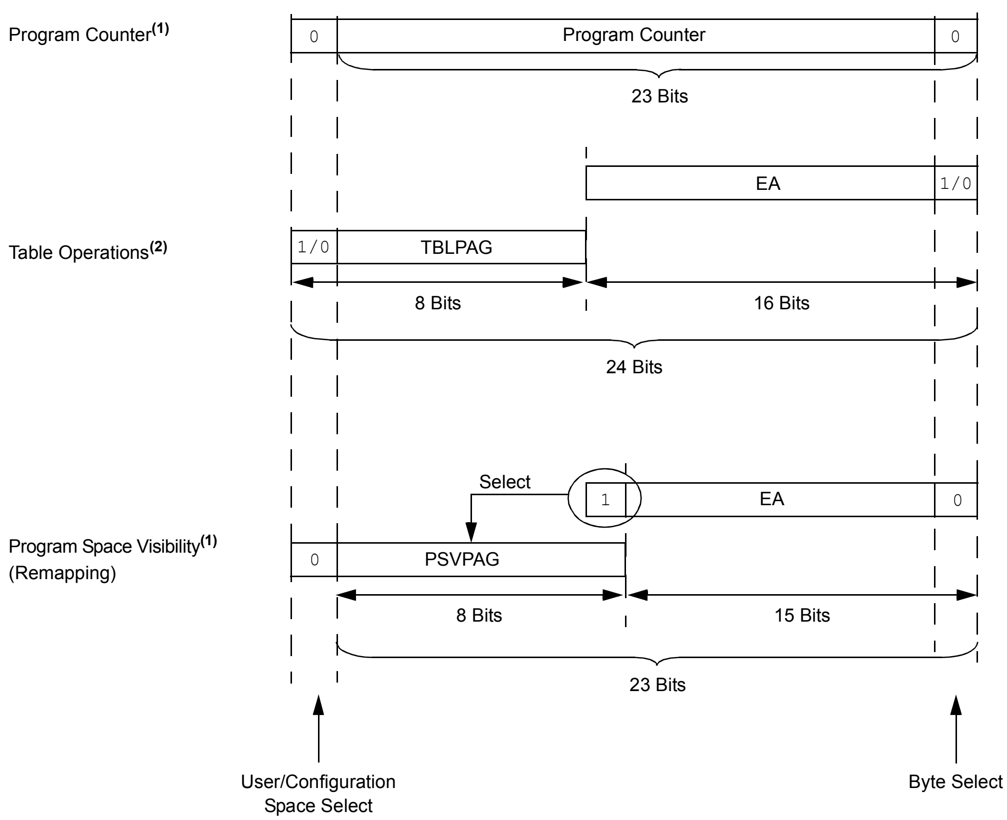
TABLE 4-27: PROGRAM SPACE ADDRESS CONSTRUCTION

Access Type	Access Space	Program Space Address				
		<23>	<22:16>	<15>	<14:1>	<0>
Instruction Access (Code Execution)	User	0	PC<22:1>			0
		0xx xxxx xxxx xxxx xxxx xxx0				
`TBLRD/TBLWT` (Byte/Word Read/Write)	User	TBLPAG<7:0>		Data EA<15:0>		
		0xxx xxxx		xxxx xxxx xxxx xxxx		
	Configuration	TBLPAG<7:0>		Data EA<15:0>		
		1xxx xxxx		xxxx xxxx xxxx xxxx		
Program Space Visibility (Block Remap/Read)	User	0	PSVPAG<7:0>[2]		Data EA<14:0>[1]	
		0	xxxx xxxx		xxx xxxx xxxx xxxx	

Note 1: Data EA<15> is always '1' in this case, but is not used in calculating the program space address. Bit 15 of the address is PSVPAG<0>.

2: PSVPAG can have only two values ('00' to access program memory and FF to access data EEPROM) in the PIC24FV32KA304 family.

FIGURE 4-5: DATA ACCESS FROM PROGRAM SPACE ADDRESS GENERATION



Note 1: The LSb of program space addresses is always fixed as '0' in order to maintain word alignment of data in the program and data spaces.

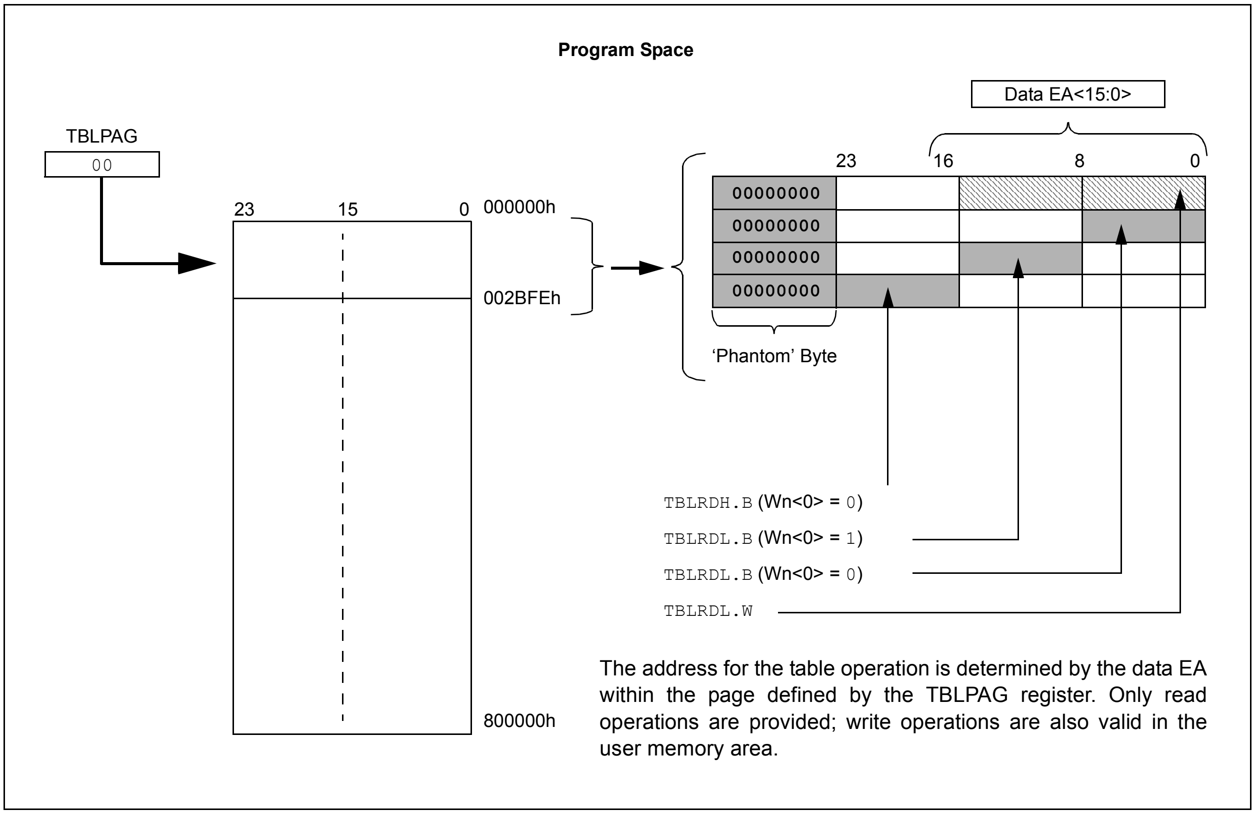
2: Table operations are not required to be word-aligned. Table read operations are permitted in the configuration memory space.

In a similar fashion, two table instructions, TBLWTH and TBLWTL, are used to write individual bytes or words to a program space address. The details of their operation are explained in **Section 5.0 "Flash Program Memory"**.

For all table operations, the area of program memory space to be accessed is determined by the Table Memory Page Address register (TBLPAG). TBLPAG covers the entire program memory space of the device, including user and configuration spaces. When TBLPAG<7> = 0, the table page is located in the user memory space. When TBLPAG<7> = 1, the page is located in configuration space.

Note:	Only Table Read operations will execute in the configuration memory space, and only then, in implemented areas, such as the Device ID. Table write operations are not allowed.

FIGURE 4-6: ACCESSING PROGRAM MEMORY WITH TABLE INSTRUCTIONS



7.2.1 POR AND LONG OSCILLATOR START-UP TIMES

The oscillator start-up circuitry and its associated delay timers are not linked to the device Reset delays that occur at power-up. Some crystal circuits (especially low-frequency crystals) will have a relatively long start-up time. Therefore, one or more of the following conditions is possible after $\overline{\text{SYSRST}}$ is released:

- The oscillator circuit has not begun to oscillate.
- The Oscillator Start-up Timer (OST) has not expired (if a crystal oscillator is used).
- The PLL has not achieved a lock (if PLL is used).

The device will not begin to execute code until a valid clock source has been released to the system. Therefore, the oscillator and PLL start-up delays must be considered when the Reset delay time must be known.

7.2.2 FAIL-SAFE CLOCK MONITOR (FSCM) AND DEVICE RESETS

If the FSCM is enabled, it will begin to monitor the system clock source when $\overline{\text{SYSRST}}$ is released. If a valid clock source is not available at this time, the device will automatically switch to the FRC oscillator and the user can switch to the desired crystal oscillator in the Trap Service Routine (TSR).

7.3 Special Function Register Reset States

Most of the Special Function Registers (SFRs) associated with the PIC24F CPU and peripherals are reset to a particular value at a device Reset. The SFRs are grouped by their peripheral or CPU function and their Reset values are specified in each section of this manual.

The Reset value for each SFR does not depend on the type of Reset with the exception of four registers. The Reset value for the Reset Control register, RCON, will depend on the type of device Reset. The Reset value for the Oscillator Control register, OSCCON, will depend on the type of Reset and the programmed values of the FNOSCx bits in the Flash Configuration Word (FOSCSEL<2:0>); see Table 7-2. The RCFGCAL and NVMCON registers are only affected by a POR.

7.4 Deep Sleep BOR (DSBOR)

Deep Sleep BOR is a very low-power BOR circuitry, used when the device is in Deep Sleep mode. Due to low current consumption, accuracy may vary.

The DSBOR trip point is around 2.0V. DSBOR is enabled by configuring DSLPBOR (FDS<6>) = `1`. DSLPBOR will re-arm the POR to ensure the device will reset if V_{DD} drops below the POR threshold.

7.5 Brown-out Reset (BOR)

The PIC24FV32KA304 family devices implement a BOR circuit, which provides the user several configuration and power-saving options. The BOR is controlled by the BORV<1:0> and BOREN<1:0> Configuration bits (FPOR<6:5,1:0>). There are a total of four BOR configurations, which are provided in Table 7-3.

The BOR threshold is set by the BORV<1:0> bits. If BOR is enabled (any values of BOREN<1:0>, except '`00`'), any drop of V_{DD} below the set threshold point will reset the device. The chip will remain in BOR until V_{DD} rises above the threshold.

If the Power-up Timer is enabled, it will be invoked after V_{DD} rises above the threshold. Then, it will keep the chip in Reset for an additional time delay, T_{PWRT}, if V_{DD} drops below the threshold while the Power-up Timer is running. The chip goes back into a BOR and the Power-up Timer will be initialized. Once V_{DD} rises above the threshold, the Power-up Timer will execute the additional time delay.

BOR and the Power-up Timer (PWRT) are independently configured. Enabling the Brown-out Reset does not automatically enable the PWRT.

7.5.1 SOFTWARE ENABLED BOR

When BOREN<1:0> = `01`, the BOR can be enabled or disabled by the user in software. This is done with the control bit, SBOREN (RCON<13>). Setting SBOREN enables the BOR to function as previously described. Clearing the SBOREN disables the BOR entirely. The SBOREN bit operates only in this mode; otherwise, it is read as '`0`'.

Placing BOR under software control gives the user the additional flexibility of tailoring the application to its environment without having to reprogram the device to change the BOR configuration. It also allows the user to tailor the incremental current that the BOR consumes. While the BOR current is typically very small, it may have some impact in low-power applications.

Note:	Even when the BOR is under software control, the Brown-out Reset voltage level is still set by the BORV<1:0> Configuration bits; it cannot be changed in software.

7.5.2 DETECTING BOR

When BOR is enabled, the BOR bit (RCON<1>) is always reset to '1' on any BOR or POR event. This makes it difficult to determine if a BOR event has occurred just by reading the state of BOR alone. A more reliable method is to simultaneously check the state of both POR and BOR. This assumes that the POR and BOR bits are reset to '0' in the software immediately after any POR event. If the BOR bit is '1' while POR is '0', it can be reliably assumed that a BOR event has occurred.

Note:	Even when the device exits from Deep Sleep mode, both the POR and BOR bits are set.

7.5.3 DISABLING BOR IN SLEEP MODE

When BOREN<1:0> = 10, BOR remains under hardware control and operates as previously described. However, whenever the device enters Sleep mode, BOR is automatically disabled. When the device returns to any other operating mode, BOR is automatically re-enabled.

This mode allows for applications to recover from brown-out situations, while actively executing code when the device requires BOR protection the most. At the same time, it saves additional power in Sleep mode by eliminating the small incremental BOR current.

Note:	BOR levels differ depending on device type; PIC24FV32KA3XX devices are at different levels than those of PIC24F32KA3XX devices. See **Section 29.0 "Electrical Characteristics"** for BOR voltage levels.

REGISTER 8-23: IPC6: INTERRUPT PRIORITY CONTROL REGISTER 6

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	T4IP2	T4IP1	T4IP0	—	—	—	—
bit 15							bit 8

U-0	R/W-1	R/W-0	R/W-0	U-0	U-0	U-0	U-0
—	OC3IP2	OC3IP1	OC3IP0	—	—	—	—
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15 **Unimplemented:** Read as ‘0’

bit 14-12 **T4IP<2:0>:** Timer4 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 11-7 **Unimplemented:** Read as ‘0’

bit 6-4 **OC3IP<2:0>:** Output Compare Channel 3 Interrupt Priority bits
111 = Interrupt is Priority 7 (highest priority interrupt)
•
•
•
001 = Interrupt is Priority 1
000 = Interrupt source is disabled

bit 3-0 **Unimplemented:** Read as ‘0’

REGISTER 10-2: DSWAKE: DEEP SLEEP WAKE-UP SOURCE REGISTER(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0, HS
—	—	—	—	—	—	—	DSINT0
bit 15							bit 8

R/W-0, HS	U-0	U-0	R/W-0, HS	R/W-0, HS	R/W-0, HS	U-0	R/W-0, HS
DSFLT	—	—	DSWDT	DSRTCC	DSMCLR	—	DSPOR(2,3)
bit 7							bit 0

Legend:	HS = Hardware Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-9 **Unimplemented:** Read as ‘0’

bit 8 **DSINT0:** Deep Sleep Interrupt-on-Change bit
1 = Interrupt-on-change was asserted during Deep Sleep
0 = Interrupt-on-change was not asserted during Deep Sleep

bit 7 **DSFLT:** Deep Sleep Fault Detect bit
1 = A Fault occurred during Deep Sleep and some Deep Sleep configuration settings may have been corrupted
0 = No Fault was detected during Deep Sleep

bit 6-5 **Unimplemented:** Read as ‘0’

bit 4 **DSWDT:** Deep Sleep Watchdog Timer Time-out bit
1 = The Deep Sleep Watchdog Timer timed out during Deep Sleep
0 = The Deep Sleep Watchdog Timer did not time out during Deep Sleep

bit 3 **DSRTCC:** Deep Sleep Real-Time Clock and Calendar (RTCC) Alarm bit
1 = The Real-Time Clock and Calendar triggered an alarm during Deep Sleep
0 = The Real-Time Clock and Calendar did not trigger an alarm during Deep Sleep

bit 2 **DSMCLR:** Deep Sleep $\overline{\text{MCLR}}$ Event bit
1 = The $\overline{\text{MCLR}}$ pin was active and was asserted during Deep Sleep
0 = The $\overline{\text{MCLR}}$ pin was not active, or was active, but not asserted during Deep Sleep

bit 1 **Unimplemented:** Read as ‘0’

bit 0 **DSPOR:** Deep Sleep Power-on Reset Event bit(2,3)
1 = The V_{DD} supply POR circuit was active and a POR event was detected
0 = The V_{DD} supply POR circuit was not active, or was active, but did not detect a POR event

Note 1: All register bits are cleared when the DSEN (DSCON<15>) bit is set.
2: All register bits are reset only in the case of a POR event outside of Deep Sleep mode, except bit, DSPOR, which does not reset on a POR event that is caused due to a Deep Sleep exit.
3: Unlike the other bits in this register, this bit can be set outside of Deep Sleep.

10.5 Doze Mode

Generally, changing clock speed and invoking one of the power-saving modes are the preferred strategies for reducing power consumption. There may be circumstances, however, where this is not practical. For example, it may be necessary for an application to maintain uninterrupted synchronous communication, even while it is doing nothing else. Reducing system clock speed may introduce communication errors, while using a power-saving mode may stop communications completely.

Doze mode is a simple and effective alternative method to reduce power consumption while the device is still executing code. In this mode, the system clock continues to operate from the same source and at the same speed. Peripheral modules continue to be clocked at the same speed, while the CPU clock speed is reduced. Synchronization between the two clock domains is maintained, allowing the peripherals to access the SFRs while the CPU executes code at a slower rate.

Doze mode is enabled by setting the DOZEN bit (CLKDIV<11>). The ratio between peripheral and core clock speed is determined by the DOZE<2:0> bits (CLKDIV<14:12>). There are eight possible configurations, from 1:1 to 1:128, with 1:1 being the default.

It is also possible to use Doze mode to selectively reduce power consumption in event driven applications. This allows clock-sensitive functions, such as synchronous communications, to continue without interruption. Meanwhile, the CPU Idles, waiting for something to invoke an interrupt routine. Enabling the automatic return to full-speed CPU operation on interrupts is enabled by setting the ROI bit (CLKDIV<15>). By default, interrupt events have no effect on Doze mode operation.

10.6 Selective Peripheral Module Control

Idle and Doze modes allow users to substantially reduce power consumption by slowing or stopping the CPU clock. Even so, peripheral modules still remain clocked, and thus, consume power. There may be cases where the application needs what these modes do not provide: the allocation of power resources to CPU processing, with minimal power consumption from the peripherals.

PIC24F devices address this requirement by allowing peripheral modules to be selectively disabled, reducing or eliminating their power consumption. This can be done with two control bits:

- The Peripheral Enable bit, generically named, “XXXEN”, located in the module’s main control SFR.
- The Peripheral Module Disable (PMD) bit, generically named, “XXXMD”, located in one of the PMD Control registers.

Both bits have similar functions in enabling or disabling its associated module. Setting the PMDx bits for a module disables all clock sources to that module, reducing its power consumption to an absolute minimum. In this state, the control and status registers associated with the peripheral will also be disabled, so writes to those registers will have no effect, and read values will be invalid. Many peripheral modules have a corresponding PMDx bit.

In contrast, disabling a module by clearing its XXXEN bit, disables its functionality, but leaves its registers available to be read and written to. Power consumption is reduced, but not by as much as the PMDx bits are used. Most peripheral modules have an enable bit; exceptions include capture, compare and RTCC.

To achieve more selective power savings, peripheral modules can also be selectively disabled when the device enters Idle mode. This is done through the control bit of the generic name format, “XXXIDL”. By default, all modules that can operate during Idle mode will do so. Using the disable on Idle feature disables the module while in Idle mode, allowing further reduction of power consumption during Idle mode, enhancing power savings for extremely critical power applications.

11.2.2 I/O PORT WRITE/READ TIMING

One instruction cycle is required between a port direction change or port write operation and a read operation of the same port. Typically, this instruction would be a `NOP`.

11.3 Input Change Notification (ICN)

The Input Change Notification function of the I/O ports allows the PIC24FV32KA304 family of devices to generate interrupt requests to the processor in response to a Change-of-State (COS) on selected input pins. This feature is capable of detecting input Change-of-States, even in Sleep mode, when the clocks are disabled. Depending on the device pin count, there are up to 23 external signals (CN0 through CN22) that may be selected (enabled) for generating an interrupt request on a Change-of-State.

There are six control registers associated with the ICN module. The CNEN1 and CNEN2 registers contain the interrupt enable control bits for each of the CN input pins. Setting any of these bits enables a CN interrupt for the corresponding pins.

Each CN pin also has a weak pull-up/pull-down connected to it. The pull-ups act as a current source that is connected to the pin. The pull-downs act as a current sink to eliminate the need for external resistors when push button or keypad devices are connected.

On any pin, only the pull-up resistor or the pull-down resistor should be enabled, but not both of them. If the push button or the keypad is connected to V_{DD}, enable the pull-down, or if they are connected to V_{SS}, enable the pull-up resistors. The pull-ups are enabled separately, using the CNPU1 and CNPU2 registers, which contain the control bits for each of the CN pins.

Setting any of the control bits enables the weak pull-ups for the corresponding pins. The pull-downs are enabled separately, using the CNPD1 and CNPD2 registers, which contain the control bits for each of the CN pins. Setting any of the control bits enables the weak pull-downs for the corresponding pins.

When the internal pull-up is selected, the pin uses V_{DD} as the pull-up source voltage. When the internal pull-down is selected, the pins are pulled down to V_{SS} by an internal resistor. Make sure that there is no external pull-up source/pull-down sink when the internal pull-ups/pull-downs are enabled.

> **Note:** Pull-ups and pull-downs on Change Notification pins should always be disabled whenever the port pin is configured as a digital output.

EXAMPLE 11-1: PORT WRITE/READ EXAMPLE

```
MOV    0xFF00, W0;          //Configure PORTB<15:8> as inputs and PORTB<7:0> as outputs
MOV    W0, TRISB;
NOP;                        //Delay 1 cycle
BTSS   PORTB, #13;          //Next Instruction

Equivalent 'C' Code
TRISB = 0xFF00;             //Configure PORTB<15:8> as inputs and PORTB<7:0> as outputs
NOP();                      //Delay 1 cycle
if(PORTBbits.RB13 == 1)     // execute following code if PORTB pin 13 is set.
{
}
```

REGISTER 16-2: SPIxCON1: SPIx CONTROL REGISTER 1

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	DISSCK	DISSDO	MODE16	SMP	CKE[1]
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
SSEN	CKP	MSTEN	SPRE2	SPRE1	SPRE0	PPRE1	PPRE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12 **DISSCK:** Disable SCKx pin bit (SPIx Master modes only)
1 = Internal SPIx clock is disabled, pin functions as an I/O
0 = Internal SPIx clock is enabled

bit 11 **DISSDO:** Disables SDOx pin bit
1 = SDOx pin is not used by the module; pin functions as an I/O
0 = SDOx pin is controlled by the module

bit 10 **MODE16:** Word/Byte Communication Select bit
1 = Communication is word-wide (16 bits)
0 = Communication is byte-wide (8 bits)

bit 9 **SMP:** SPIx Data Input Sample Phase bit
Master mode:
1 = Input data is sampled at the end of data output time
0 = Input data is sampled at the middle of data output time
Slave mode:
SMP must be cleared when SPIx is used in Slave mode.

bit 8 **CKE:** Clock Edge Select bit[1]
1 = Serial output data changes on transition from active clock state to Idle clock state (see bit 6)
0 = Serial output data changes on transition from Idle clock state to active clock state (see bit 6)

bit 7 **SSEN:** Slave Select Enable bit (Slave mode)
1 = $\overline{SSx}$ pin is used for Slave mode
0 = $\overline{SSx}$ pin is not used by the module; pin is controlled by port function

bit 6 **CKP:** Clock Polarity Select bit
1 = Idle state for clock is a high level; active state is a low level
0 = Idle state for clock is a low level; active state is a high level

bit 5 **MSTEN:** Master Mode Enable bit
1 = Master mode
0 = Slave mode

bit 4-2 **SPRE<2:0>:** Secondary Prescale bits (Master mode)
111 = Secondary prescale 1:1
110 = Secondary prescale 2:1
.
.
.
000 = Secondary prescale 8:1

Note 1: The CKE bit is not used in the Framed SPI modes. The user should program this bit to ‘0’ for the Framed SPI modes (FRMEN = 1).

19.2.5 RTCVAL REGISTER MAPPINGS

REGISTER 19-4: YEAR: YEAR VALUE REGISTER(1)

U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
—	—	—	—	—	—	—	—
bit 15							bit 8

R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
YRTEN3	YRTEN2	YRTEN2	YRTEN1	YRONE3	YRONE2	YRONE1	YRONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **Unimplemented:** Read as ‘0’

bit 7-4 **YRTEN<3:0>:** Binary Coded Decimal Value of Year’s Tens Digit bits
Contains a value from 0 to 9.

bit 3-0 **YRONE<3:0>:** Binary Coded Decimal Value of Year’s Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to the YEAR register is only allowed when RTCWREN = 1.

REGISTER 19-5: MTHDY: MONTH AND DAY VALUE REGISTER(1)

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	MTHTEN0	MTHONE3	MTHONE2	MTHONE1	MTHONE0
bit 15							bit 8

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	DAYTEN1	DAYTEN0	DAYONE3	DAYONE2	DAYONE1	DAYONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12 **MTHTEN0:** Binary Coded Decimal Value of Month’s Tens Digit bit
Contains a value of ‘0’ or ‘1’.

bit 11-8 **MTHONE<3:0>:** Binary Coded Decimal Value of Month’s Ones Digit bits
Contains a value from 0 to 9.

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-4 **DAYTEN<1:0>:** Binary Coded Decimal Value of Day’s Tens Digit bits
Contains a value from 0 to 3.

bit 3-0 **DAYONE<3:0>:** Binary Coded Decimal Value of Day’s Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to this register is only allowed when RTCWREN = 1.

19.2.6 ALRMVAL REGISTER MAPPINGS

REGISTER 19-8: ALMTHDY: ALARM MONTH AND DAY VALUE REGISTER(1)

U-0	U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	—	MTHTEN0	MTHONE3	MTHONE2	MTHONE1	MTHONE0
bit 15							bit 8

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	DAYTEN1	DAYTEN0	DAYONE3	DAYONE2	DAYONE1	DAYONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as ‘0’

bit 12 **MTHTEN0:** Binary Coded Decimal Value of Month’s Tens Digit bit
Contains a value of ‘0’ or ‘1’.

bit 11-8 **MTHONE<3:0>:** Binary Coded Decimal Value of Month’s Ones Digit bits
Contains a value from 0 to 9.

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-4 **DAYTEN<1:0>:** Binary Coded Decimal Value of Day’s Tens Digit bits
Contains a value from 0 to 3.

bit 3-0 **DAYONE<3:0>:** Binary Coded Decimal Value of Day’s Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to this register is only allowed when RTCWREN = 1.

REGISTER 19-9: ALWDHR: ALARM WEEKDAY AND HOURS VALUE REGISTER(1)

U-0	U-0	U-0	U-0	U-0	R/W-x	R/W-x	R/W-x
—	—	—	—	—	WDAY2	WDAY1	WDAY0
bit 15							bit 8

U-0	U-0	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
—	—	HRTEN1	HRTEN0	HRONE3	HRONE2	HRONE1	HRONE0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-11 **Unimplemented:** Read as ‘0’

bit 10-8 **WDAY<2:0>:** Binary Coded Decimal Value of Weekday Digit bits
Contains a value from 0 to 6.

bit 7-6 **Unimplemented:** Read as ‘0’

bit 5-4 **HRTEN<1:0>:** Binary Coded Decimal Value of Hour’s Tens Digit bits
Contains a value from 0 to 2.

bit 3-0 **HRONE<3:0>:** Binary Coded Decimal Value of Hour’s Ones Digit bits
Contains a value from 0 to 9.

Note 1: A write to this register is only allowed when RTCWREN = 1.

26.2 On-Chip Voltage Regulator

All of the PIC24FV32KA304 family devices power their core digital logic at a nominal 3.0V. This may create an issue for designs that are required to operate at a higher typical voltage, as high as 5.0V. To simplify system design, all devices in the “FV” family incorporate an on-chip regulator that allows the device to run its core logic from V_{DD}.

The regulator is always enabled and provides power to the core from the other V_{DD} pins. A low-ESR capacitor (such as ceramic) must be connected to the V_{CAP} pin (Figure 26-1). This helps to maintain the stability of the regulator. The recommended value for the filter capacitor is discussed in **Section 2.4 “Voltage Regulator Pin (V_{CAP})”**, and in **Section 29.1 “DC Characteristics”**.

For “F” devices, the regulator is disabled. Instead, core logic is powered directly from V_{DD}. This allows the devices to operate at an overall lower allowable voltage range (1.8V-3.6V).

26.2.1 VOLTAGE REGULATOR TRACKING MODE AND LOW-VOLTAGE DETECTION

For all PIC24FV32KA304 devices, the on-chip regulator provides a constant voltage of 3.2V nominal to the digital core logic. The regulator can provide this level from a V_{DD} of about 3.2V, all the way up to the device’s V_{DDMAX}. It does not have the capability to boost V_{DD} levels below 3.2V. In order to prevent “brown-out” conditions when the voltage drops too low for the regulator, the regulator enters Tracking mode. In Tracking mode, the regulator output follows V_{DD} with a typical voltage drop of 150 mV.

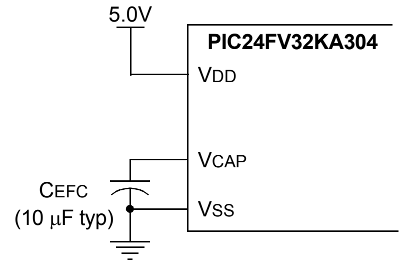
When the device enters Tracking mode, it is no longer possible to operate at full speed. To provide information about when the device enters Tracking mode, the on-chip regulator includes a simple, High/Low-Voltage Detect (HLVD) circuit. When V_{DD} drops below full-speed operating voltage, the circuit sets the High/Low-Voltage Detect Interrupt Flag, HLVDIF (IFS4<8>). This can be used to generate an interrupt and put the application into a low-power operational mode or trigger an orderly shutdown. Maximum device speeds as a function of V_{DD} are shown in **Section 29.1 “DC Characteristics”**, in Figure 29-1 and Figure 29-1.

26.2.2 ON-CHIP REGULATOR AND POR

For PIC24FV32KA304 devices, it takes a brief time, designated as T_{PM}, for the Voltage Regulator to generate a stable output. During this time, code execution is disabled. T_{PM} (DC Specification SY71) is applied every time the device resumes operation after any power-down, including Sleep mode.

FIGURE 26-1: CONNECTIONS FOR THE ON-CHIP REGULATOR

Regulator Enabled[1]:



Note 1: These are typical operating voltages. Refer to **Section 29.0 “Electrical Characteristics”** for the full operating ranges of V_{DD}.

26.3 Watchdog Timer (WDT)

For the PIC24FV32KA304 family of devices, the WDT is driven by the LPRC oscillator. When the WDT is enabled, the clock source is also enabled.

The nominal WDT clock source from LPRC is 31 kHz. This feeds a prescaler that can be configured for either 5-bit (divide-by-32) or 7-bit (divide-by-128) operation. The prescaler is set by the FWPSA Configuration bit. With a 31 kHz input, the prescaler yields a nominal WDT time-out period (T_{WDT}) of 1 ms in 5-bit mode or 4 ms in 7-bit mode.

A variable postscaler divides down the WDT prescaler output and allows for a wide range of time-out periods. The postscaler is controlled by the Configuration bits, WDTPS<3:0> (FWDT<3:0>), which allow the selection of a total of 16 settings, from 1:1 to 1:32,768. Using the prescaler and postscaler time-out periods, ranging from 1 ms to 131 seconds, can be achieved.

The WDT, prescaler and postscaler are reset:

- On any device Reset
- On the completion of a clock switch, whether invoked by software (i.e., setting the OSWEN bit after changing the NOSCx bits) or by hardware (i.e., Fail-Safe Clock Monitor)
- When a `PWRSAV` instruction is executed (i.e., Sleep or Idle mode is entered)
- When the device exits Sleep or Idle mode to resume normal operation
- By a `CLRWDT` instruction during normal execution

27.2 MPLAB C Compilers for Various Device Families

The MPLAB C Compiler code development systems are complete ANSI C compilers for Microchip's PIC18, PIC24 and PIC32 families of microcontrollers and the dsPIC30 and dsPIC33 families of digital signal controllers. These compilers provide powerful integration capabilities, superior code optimization and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

27.3 HI-TECH C for Various Device Families

The HI-TECH C Compiler code development systems are complete ANSI C compilers for Microchip's PIC family of microcontrollers and the dsPIC family of digital signal controllers. These compilers provide powerful integration capabilities, omniscient code generation and ease of use.

For easy source level debugging, the compilers provide symbol information that is optimized to the MPLAB IDE debugger.

The compilers include a macro assembler, linker, preprocessor, and one-step driver, and can run on multiple platforms.

27.4 MPASM Assembler

The MPASM Assembler is a full-featured, universal macro assembler for PIC10/12/16/18 MCUs.

The MPASM Assembler generates relocatable object files for the MPLINK Object Linker, Intel® standard HEX files, MAP files to detail memory usage and symbol reference, absolute LST files that contain source lines and generated machine code and COFF files for debugging.

The MPASM Assembler features include:

- Integration into MPLAB IDE projects
- User-defined macros to streamline assembly code
- Conditional assembly for multi-purpose source files
- Directives that allow complete control over the assembly process

27.5 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK Object Linker combines relocatable objects created by the MPASM Assembler and the MPLAB C18 C Compiler. It can link relocatable objects from precompiled libraries, using directives from a linker script.

The MPLIB Object Librarian manages the creation and modification of library files of precompiled code. When a routine from a library is called from a source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications.

The object linker/library features include:

- Efficient linking of single libraries instead of many smaller files
- Enhanced code maintainability by grouping related modules together
- Flexible creation of libraries with easy module listing, replacement, deletion and extraction

27.6 MPLAB Assembler, Linker and Librarian for Various Device Families

MPLAB Assembler produces relocatable machine code from symbolic assembly language for PIC24, PIC32 and dsPIC devices. MPLAB C Compiler uses the assembler to produce its object file. The assembler generates relocatable object files that can then be archived or linked with other relocatable object files and archives to create an executable file. Notable features of the assembler include:

- Support for the entire device instruction set
- Support for fixed-point and floating-point data
- Command line interface
- Rich directive set
- Flexible macro language
- MPLAB IDE compatibility

TABLE 29-7: DC CHARACTERISTICS: IDLE CURRENT (IIDLE)

DC CHARACTERISTICS		Standard Operating Conditions: 1.8V to 3.6V PIC24F32KA3XX; 2.0V to 5.5V PIC24FV32KA3XX. Operating temperature: -40°C ≤ TA ≤ +85°C for Industrial; -40°C ≤ TA ≤ +125°C for Extended				
Parameter No.	Device	Typical	Max	Units	Conditions	
Idle Current (IIDLE)						
DC40	PIC24FV32KA3XX	120	200	µA	2.0V	0.5 MIPS, FOSC = 1 MHz(1)
		160	430	µA	5.0V	
	PIC24F32KA3XX	50	100	µA	1.8V	
		90	370	µA	3.3V	
DC42	PIC24FV32KA3XX	165	—	µA	2.0V	1 MIPS, FOSC = 2 MHz(1)
		260	—	µA	5.0V	
	PIC24F32KA3XX	95	—	µA	1.8V	
		180	—	µA	3.3V	
DC44	PIC24FV32KA3XX	3.1	6.5	mA	5.0V	16 MIPS, FOSC = 32 MHz(1)
	PIC24F32KA3XX	2.9	6.0	mA	3.3V	
DC46	PIC24FV32KA3XX	0.65	—	mA	2.0V	FRC (4 MIPS), FOSC = 8 MHz
		1.0	—	mA	5.0V	
	PIC24F32KA3XX	0.55	—	mA	1.8V	
		1.0	—	mA	3.3V	
DC50	PIC24FV32KA3XX	60	200	µA	2.0V	LPRC (15.5 KIPS), FOSC = 31 kHz
		70	350	µA	5.0V	
	PIC24F32KA3XX	2.2	18	µA	1.8V	
		4.0	60	µA	3.3V	

Legend: Unshaded rows represent PIC24F32KA3XX devices and shaded rows represent PIC24FV32KA3XX devices.

Note 1: Oscillator is in External Clock mode (FOSCSEL<2:0> = `010`, FOSC<1:0> = `00`).

TABLE 29-10: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V PIC24F32KA3XX 2.0V to 5.5V PIC24FV32KA3XX Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended					
Param No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**	
	VOL	**Output Low Voltage**						
DO10		All I/O Pins	—	—	0.4	V	IOL = 8.0 mA	VDD = 4.5V
			—	—	0.4	V	IOL = 4.0 mA	VDD = 3.6V
			—	—	0.4	V	IOL = 3.5 mA	VDD = 2.0V
DO16		OSC2/CLKO	—	—	0.4	V	IOL = 2.0 mA	VDD = 4.5V
			—	—	0.4	V	IOL = 1.2 mA	VDD = 3.6V
			—	—	0.4	V	IOL = 0.4 mA	VDD = 2.0V
	VOH	**Output High Voltage**						
DO20		All I/O Pins	3.8	—	—	V	IOH = -3.5 mA	VDD = 4.5V
			3	—	—	V	IOH = -3.0 mA	VDD = 3.6V
			1.6	—	—	V	IOH = -1.0 mA	VDD = 2.0V
DO26		OSC2/CLKO	3.8	—	—	V	IOH = -2.0 mA	VDD = 4.5V
			3	—	—	V	IOH = -1.0 mA	VDD = 3.6V
			1.6	—	—	V	IOH = -0.5 mA	VDD = 2.0V

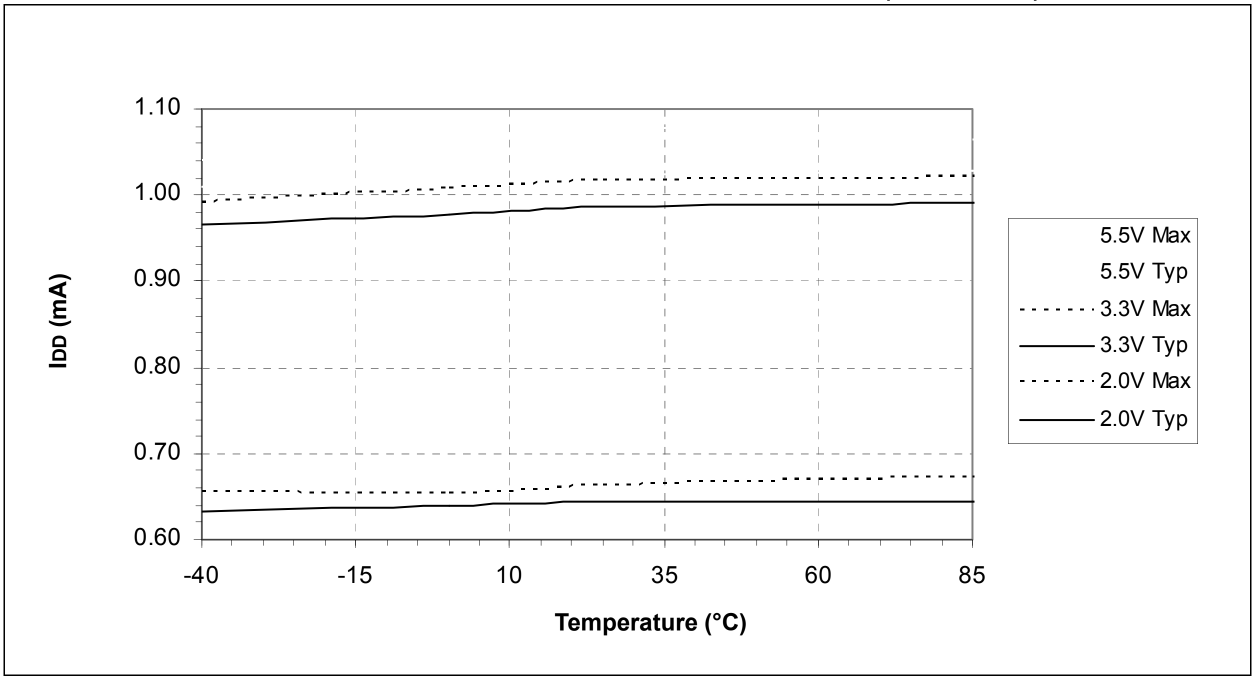
Note 1: Data in “Typ” column is at +25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

TABLE 29-11: DC CHARACTERISTICS: PROGRAM MEMORY

DC CHARACTERISTICS			Standard Operating Conditions: 1.8V to 3.6V PIC24F32KA3XX 2.0V to 5.5V PIC24FV32KA3XX Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Sym**	**Characteristic**	**Min**	**Typ(1)**	**Max**	**Units**	**Conditions**
		Program Flash Memory					
D130	EP	Cell Endurance	10,000(2)	—	—	E/W	
D131	VPR	VDD for Read	VMIN	—	3.6	V	VMIN = Minimum operating voltage
D133A	TIW	Self-Timed Write Cycle Time	—	2	—	ms	
D134	TRETD	Characteristic Retention	40	—	—	Year	Provided no other specifications are violated
D135	IDDP	Supply Current During Programming	—	10	—	mA	

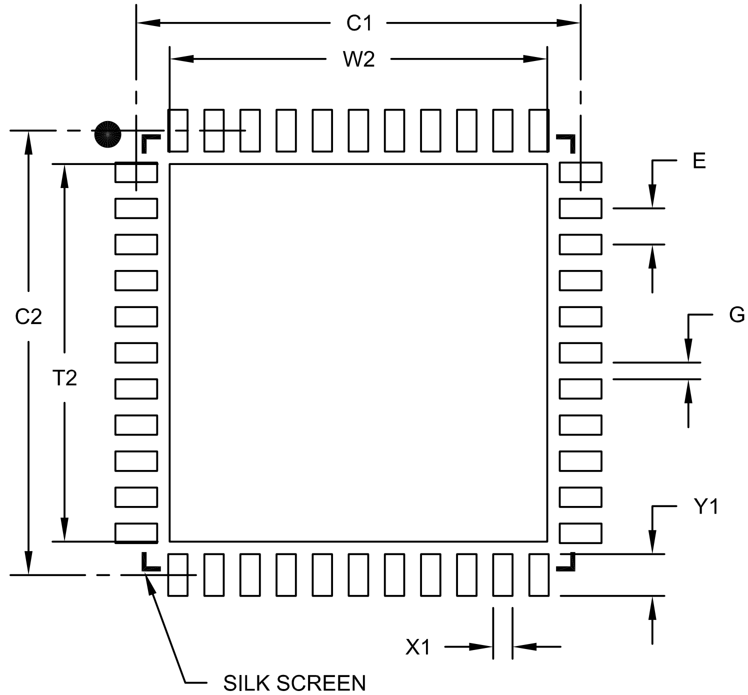
Note 1: Data in “Typ” column is at 3.3V, +25°C unless otherwise stated.
2: Self-write and block erase.

FIGURE 30-9: TYPICAL AND MAXIMUM I_{IDLE} vs. TEMPERATURE (FRC MODE)



44-Lead Plastic Quad Flat, No Lead Package (ML) - 8x8 mm Body [QFN]

Note:	For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.65 BSC		
Optional Center Pad Width	W2			6.60
Optional Center Pad Length	T2			6.60
Contact Pad Spacing	C1		8.00	
Contact Pad Spacing	C2		8.00	
Contact Pad Width (X44)	X1			0.35
Contact Pad Length (X44)	Y1			0.85
Distance Between Pads	G	0.25		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2103B

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Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

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